

## PRESS RELEASE

### **Aurora Semiconductor and BRIDG Form Strategic Alliance for High Technology 200mm Wafer Production**

ST. PETERSBURG, FL and NEOCITY, FL; July 10, 2017 (GLOBE NEWSWIRE) -- Aurora Semiconductor, LLC and BRIDG have signed a Letter of Intent to collaborate in the Osceola-based Public-Private Partnership to support the technology development and manufacturing deployment of Aurora's 4D Heterogenous System in Package (4DHSiP™) technology.

The unique capability of Aurora's 4DHSiP™ technology enables the placement of over 100 components in a single package the size of a thumb nail, with the thickness of a credit card. This package can be stacked up to 5 high, containing 500 components and 70 interconnect layers on a heterogenous basis. This is an astonishing reduction in size, weight and power consumption, creating tremendous potential for 4DHSiP™ in markets such as aerospace, interconnect systems, medical, servers, internet of things, smart machines and automotive. No other company in the world has this capability.

"We are tremendously excited about our strategic alliance with BRIDG. This relationship will provide Aurora with access to the 200mm fab capacity essential for our 4DHSiP™ growth strategy to be fully-optimized economically. It will also enable Aurora to better-network with sources of funding to support the infrastructure necessary to drive 4DHSiP™ into its target markets. We could not ask for a better partner," stated Gary Breton, CEO of Aurora Semiconductor.

BRIDG's 109,000 sq. ft. state-of-the-art facility in NeoCity, FL includes approx. 40,000 sq. ft. of cleanroom laboratory/manufacturing space for use by its industry partners. BRIDG deploys its unique collaboration model within a state-of-the-art manufacturing facility focused on semiconductor-based processes for smart sensors, photonic technologies, and next generation integrated devices. The result enables unparalleled innovative breakthroughs for these industry partners serving government and commercial markets.

"This latest partnership with Aurora is a perfect example of how the investments made in establishing the BRIDG infrastructure enable business to grow and expand product offerings while building the foundation for more high tech job opportunities in Florida. We are proud to collaborate with Aurora and continue building strategic alliances in support of innovation," stated Chester Kennedy, CEO of BRIDG.

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#### **About Aurora**

Aurora Semiconductor manufactures multichip modules with a licensed 4D Heterogenous System in Package (4DHSiP™) technology and with a proprietary stacking methodology. This IP enables Aurora's customers to deploy their system and heterogeneous integration applications in the world's smallest footprint and highest density interconnect packaging. Headquartered in St. Petersburg, Florida, Aurora operates a secure facility with site secret clearance. For more information, please visit [www.aurorasemi.com](http://www.aurorasemi.com).

#### **About BRIDG**

BRIDG is an industry-led collaborative partnership for advanced sensors, optics and photonics and other advanced manufacturing devices, focusing on the development of innovative manufacturable processes, materials and equipment for next-generation smart sensors and other future high-tech products. Supported by Osceola County, the University of Central Florida and the Florida High Tech Corridor Council, BRIDG facilitates the connection between innovation and industry – thus "bridging the innovation development gap" that makes commercialization possible. Headquartered in NeoCity, Florida, BRIDG is the anchor of a 500-acre master-planned intuitive community of innovation, where it operates one of the world's most flexible and adaptable fabs to accommodate partner-funded activities. Learn more at [www.GoBRIDG.com](http://www.GoBRIDG.com).